

Fiber-to-chip packaging of AMF chips with photonic wire bonds (PWB)



Advantages of photonic wire bonds

- Fast 3D fabrication of optical connection (30 to 120 seconds per bond)
- Low optical insertion loss (< 3 dB per bond)
- High placement and optical misalignment tolerance (< 30 μm)
- Compact and mechanically stable
- Flexible - can accommodate components with disparate mode field size/shape
- Low-volume prototyping, and potential for up to million units production



Contact AMF and/or Dream Photonics for more information, custom solutions, and cost



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